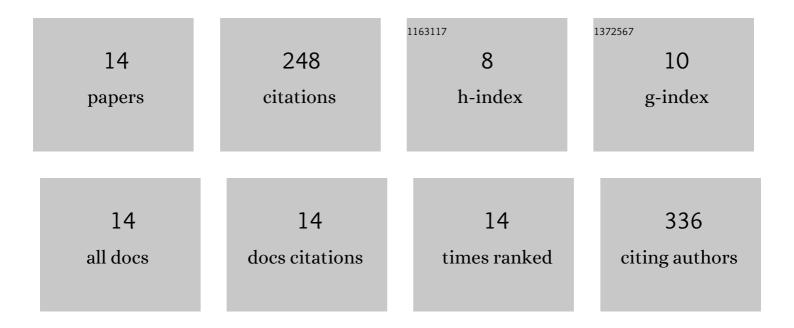
Di Jiang

List of Publications by Year in descending order

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| # | Article | IF | CITATIONS |
|----|---|------|-----------|
| 1 | A flexible and stackable 3D interconnect system using growth-engineered carbon nanotube scaffolds. Flexible and Printed Electronics, 2017, 2, 025003. | 2.7 | 6 |
| 2 | Embedded Fin‣ike Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016, 12, 1521-1526. | 10.0 | 15 |
| 3 | Flexible Multifunctionalized Carbon Nanotubesâ€Based Hybrid Nanowires. Advanced Functional Materials, 2015, 25, 4135-4143. | 14.9 | 20 |
| 4 | Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. Journal of Electronic Materials, 2015, 44, 2898-2907. | 2.2 | 21 |
| 5 | Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. IEEE Electron Device Letters, 2015, 36, 499-501. | 3.9 | 44 |
| 6 | Reliability of carbon nanotube bumps for chip on glass application. , 2014, , . | | 2 |
| 7 | Carbon nanotube/solder hybrid structure for interconnect applications. , 2014, , . | | 0 |
| 8 | Chemically vapor deposited carbon nanotubes for vertical electronics interconnect in packaging applications. , 2014, , . | | 2 |
| 9 | Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. Advances in Manufacturing, 2013, 1, 13-27. | 6.1 | 22 |
| 10 | Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in Manufacturing, 2013, 1, 236-240. | 6.1 | 2 |
| 11 | Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180. | 2.4 | 30 |
| 12 | Reliability of carbon nanotube bumps for chip on film application. , 2013, , . | | 0 |
| 13 | Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. IEEE Electron Device Letters, 2012, 33, 420-422. | 3.9 | 67 |
| 14 | Formation of three-dimensional carbon nanotube structures by controllable vapor densification. Materials Letters, 2012, 78, 184-187. | 2.6 | 17 |